



YOUSHANG SEMICONDUCTOR

**设计研发新型功率器件**

**各类小信号开关**

**中低压及高压大电流等场效应管**

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## Features

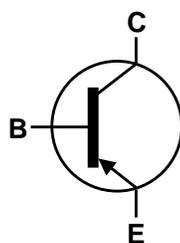
- Epitaxial Planar Die Construction
- Ideal for Low Power Amplification and Switching
- Complementary NPN Type: NK-MMBT2222AQ

## Mechanical Data

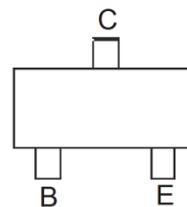
- Package: SOT23
- Package Material: Molded Plastic, "Green" Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 
- Weight: 0.008 grams (Approximate)



Top View



Device Symbol



Top View  
Pin-Out

**Absolute Maximum Ratings** (@  $T_A = +25^{\circ}\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	$V_{CBO}$	-60	V
Collector-Emitter Voltage	$V_{CEO}$	-60	V
Emitter-Base Voltage	$V_{EBO}$	-6.0	V
Collector Current	$I_C$	-600	mA
Peak Collector Current	$I_{CM}$	-800	mA
Peak Base Current	$I_{BM}$	-200	mA

**Thermal Characteristics**

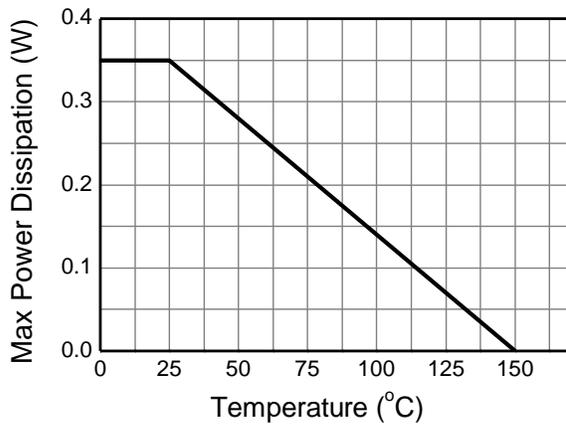
Characteristic	Symbol	Value	Unit
Collector Power Dissipation	$P_D$	310	mW
		350	
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	403	$^{\circ}\text{C/W}$
		357	
Thermal Resistance, Junction to Leads	$R_{\theta JL}$	350	$^{\circ}\text{C/W}$
Thermal Resistance, Junction to Case	$R_{\theta JC}$	120	$^{\circ}\text{C/W}$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	$^{\circ}\text{C}$

**ESD Ratings** (Note 8)

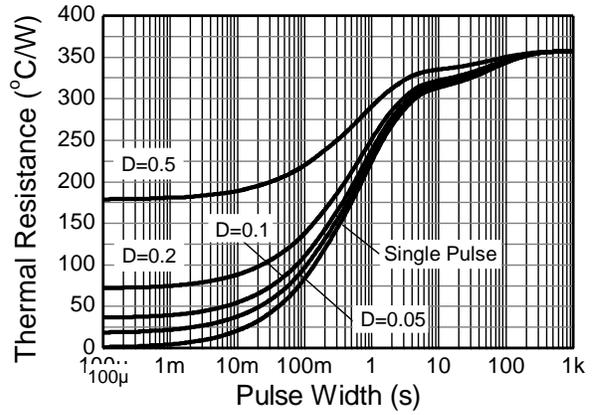
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
5. For a device mounted on minimum recommended pad layout 1oz copper that is on a single-sided FR-4 PCB; device is measured under still air conditions whilst operating in a steady-state.
  6. Same as Note 5, except the device is mounted on 15 mm x 15mm 1oz copper.
  7. Thermal resistance from junction to solder-point (at the end of the leads).
  8. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

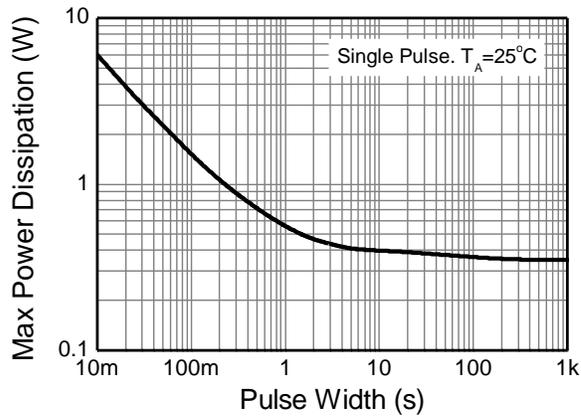
## Thermal Characteristics and Derating Information



**Derating Curve**



**Transient Thermal Impedance**



**Pulse Power Dissipation**

**Electrical Characteristics** (@  $T_A = +25^\circ\text{C}$ , unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
<b>OFF CHARACTERISTICS</b>					
Collector-Base Breakdown Voltage	$BV_{CBO}$	-60	—	V	$I_C = -100\mu\text{A}$ , $I_E = 0$
Collector-Emitter Breakdown Voltage (Note 9)	$BV_{CEO}$	-60	—	V	$I_C = -10\text{mA}$ , $I_B = 0$
Emitter-Base Breakdown Voltage	$BV_{EBO}$	-6.0	—	V	$I_E = -100\mu\text{A}$ , $I_C = 0$
Collector Cut-Off Current	$I_{CBO}$	—	-10	nA	$V_{CB} = -50\text{V}$ , $I_E = 0$
			-10	$\mu\text{A}$	$V_{CB} = -50\text{V}$ , $I_E = 0$ , $T_A = +125^\circ\text{C}$
Collector Cut-Off Current	$I_{CEX}$	—	-50	nA	$V_{CE} = -30\text{V}$ , $V_{EB(\text{off})} = -0.5\text{V}$
Base Cut-Off Current	$I_{BL}$	—	-50	nA	$V_{CE} = -30\text{V}$ , $V_{EB(\text{off})} = -0.5\text{V}$
Emitter Cut-Off Current	$I_{EBO}$	—	-50	nA	$V_{EB} = -6.0\text{V}$
<b>ON CHARACTERISTICS (Note 9)</b>					
DC Current Gain	$h_{FE}$	75	—	—	$I_C = -100\mu\text{A}$ , $V_{CE} = -10\text{V}$
		100	—		$I_C = -1.0\text{mA}$ , $V_{CE} = -10\text{V}$
		100	—		$I_C = -10\text{mA}$ , $V_{CE} = -10\text{V}$
		100	300		$I_C = -150\text{mA}$ , $V_{CE} = -10\text{V}$
		50	—		$I_C = -500\text{mA}$ , $V_{CE} = -10\text{V}$
Collector-Emitter Saturation Voltage	$V_{CE(\text{sat})}$	—	-0.4 -1.6	V	$I_C = -150\text{mA}$ , $I_B = -15\text{mA}$ $I_C = -500\text{mA}$ , $I_B = -50\text{mA}$
Base-Emitter Saturation Voltage	$V_{BE(\text{sat})}$	—	-1.3 -2.6	V	$I_C = -150\text{mA}$ , $I_B = -15\text{mA}$ $I_C = -500\text{mA}$ , $I_B = -50\text{mA}$
<b>SMALL SIGNAL CHARACTERISTICS</b>					
Output Capacitance	$C_{obo}$	—	8.0	pF	$V_{CB} = -10\text{V}$ , $f = 1.0\text{MHz}$ , $I_E = 0$
Input Capacitance	$C_{ibo}$	—	30	pF	$V_{EB} = -2.0\text{V}$ , $f = 1.0\text{MHz}$ , $I_C = 0$
Current Gain-Bandwidth Product	$f_T$	200	—	MHz	$V_{CE} = -20\text{V}$ , $I_C = -50\text{mA}$ , $f = 100\text{MHz}$
<b>SWITCHING CHARACTERISTICS</b>					
Turn-On Time	$t_{on}$	—	45	ns	$V_{CC} = -30\text{V}$ , $I_C = -150\text{mA}$ , $I_{B1} = -15\text{mA}$
Delay Time	$t_d$	—	10	ns	
Rise Time	$t_r$	—	40	ns	
Turn-Off Time	$t_{off}$	—	100	ns	$V_{CC} = -6.0\text{V}$ , $I_C = -150\text{mA}$ , $I_{B1} = -I_{B2} = -15\text{mA}$
Storage Time	$t_s$	—	80	ns	
Fall Time	$t_f$	—	30	ns	

 Note: 9. Measured under pulsed conditions. Pulse width  $\leq 300\mu\text{s}$ . Duty cycle  $\leq 2\%$ .

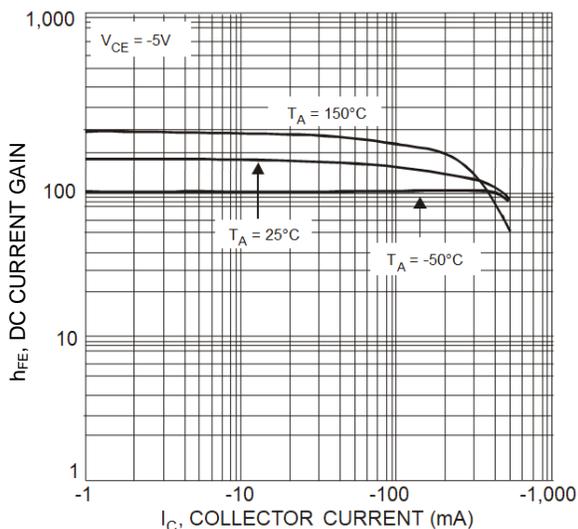


Fig. 1 Typical DC Current Gain vs. Collector Current

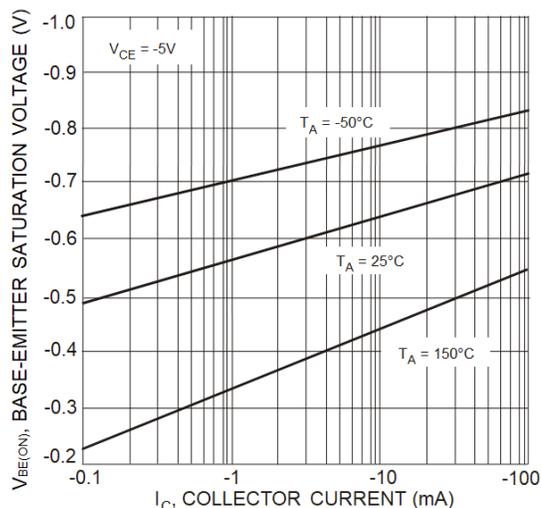


Fig. 2 Typical Base-Emitter Saturation Voltage vs. Collector Current

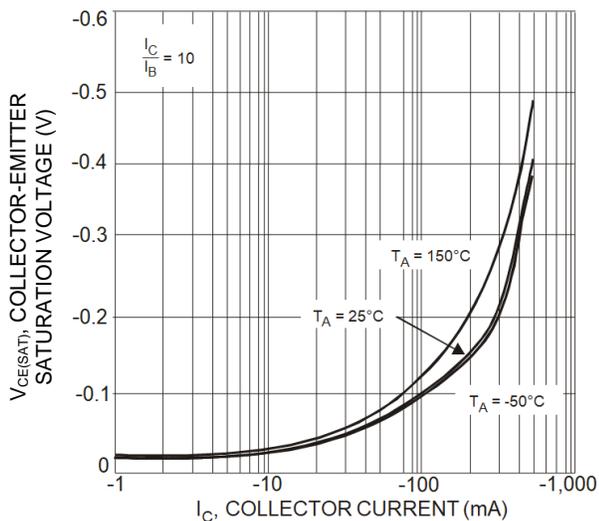


Fig. 3 Typical Collector-Emitter Saturation Voltage vs. Collector Current

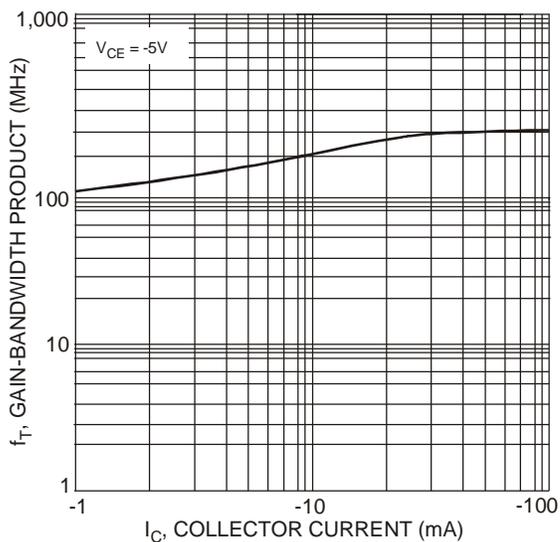


Fig. 4 Typical Gain-Bandwidth Product vs. Collector Current

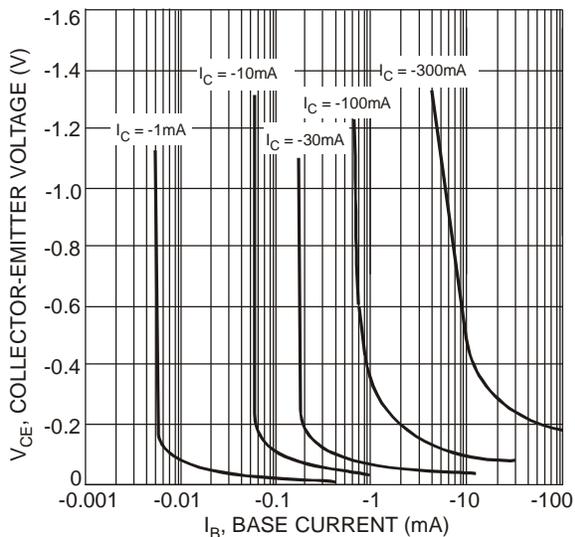


Fig. 5 Typical Collector Saturation Region

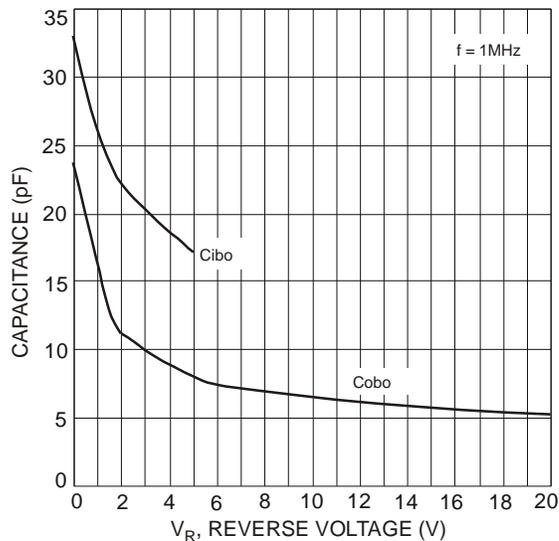
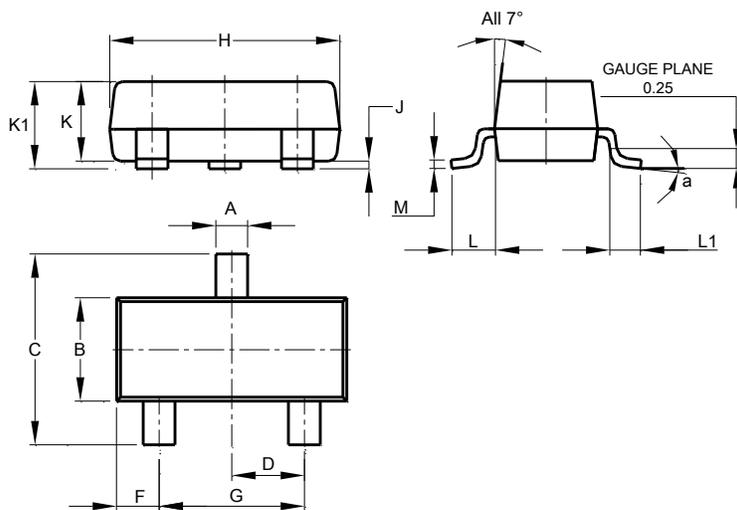


Fig. 6 Typical Capacitance Characteristics

## Package Outline Dimensions

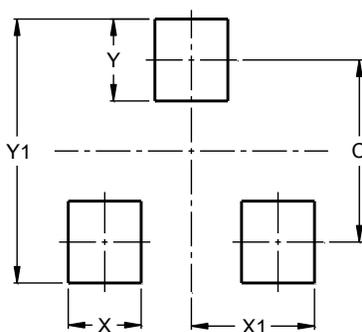
SOT23



SOT23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.890	1.00	0.975
K1	0.903	1.10	1.025
L	0.45	0.61	0.55
L1	0.25	0.55	0.40
M	0.085	0.150	0.110
a	0°	8°	--
All Dimensions in mm			

## Suggested Pad Layout

SOT23



Dimensions	Value (in mm)
C	2.0
X	0.8
X1	1.35
Y	0.9
Y1	2.9